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(54) **COMPONENT-EMBEDDED SUBSTRATE**

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(71) Applicant: **Fujikura Ltd.**, Tokyo (JP)

(72) Inventors: **Masakazu Sato**, Tokyo (JP); **Nobuki Ueta**, Tokyo (JP); **Yoshio Nakao**, Tokyo (JP); **Masatoshi Inaba**, Tokyo (JP)

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(73) Assignee: **Fujikura Ltd.**, Tokyo (JP)

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(57) **ABSTRACT**

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A component-embedded substrate includes: a plurality of insulating layers each including a wiring pattern formed on one surface; an embedded component including a connection terminal; and a plurality of vias that electrically connect the connection terminal to the wiring patterns adjacent to each other in a lamination direction. The plurality of insulating layers is laminated on the connection terminal. Each of the plurality of vias is composed of a via hole formed in the respective insulating layer of the plurality of the insulating layers and a conductive material provided in the via hole. One of the plurality of vias is a connection via directly connected to the connection terminal. Another of the plurality of vias is a first adjacent via adjacent to the connection via in the lamination direction. The first adjacent via is connected to the wiring pattern formed on a surface of a top insulating layer.

